

**Polymer  
PTC Devices**

Surface mount fuses

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**LP-ISM020**

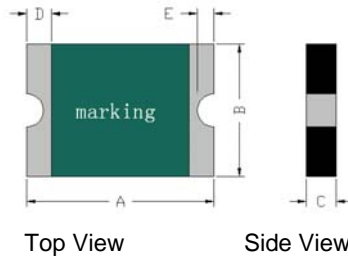
**Features**

- Small size of 0805
- Lead-free and compliant with the European Union RoHS Directive 2002/95/EC
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL pending



**Product Dimensions (mm)**

Part number	A Max.	B Max.	C Max.	D Min.	E Min.	Part marking
LP-ISM020	2.20	1.50	1.00	0.10	0.20	2

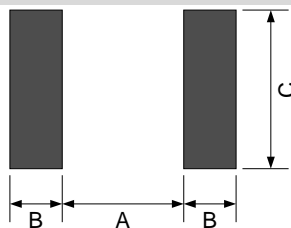


**Electrical Characteristics**

Part number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> Current(A) Time(S)	P <sub>d typ</sub> (W)	R <sub>min</sub> (Ω)	R <sub>1max</sub> (Ω)
LP-ISM020	0.20	0.50	9.00	40.0	8.00 0.02	0.5	0.65	3.50

I<sub>H</sub>=Hold current: maximum current at which the device will not trip at 25°C still air.  
I<sub>T</sub>=Trip current: minimum current at which the device will always trip at 25°C still air.  
V<sub>max</sub>=Maximum voltage device can withstand without damage at rated current.  
I<sub>max</sub>=Maximum fault current device can withstand without damage at rated voltage.  
T<sub>trip</sub>=Maximum time to trip(s) at assigned current.  
P<sub>d typ</sub>=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.  
R<sub>min</sub>=Minimum device resistance at 25°C prior to tripping.  
R<sub>1max</sub>=Maximum device resistance measured in the nontripped state 1 hour post reflow.

**Solder Reflow Recommendations**



**Solder Pad Layouts**

Part number	A (mm)	B (mm)	C (mm)
LP-ISM020	1.20	1.00	1.50

\* Recommended reflow methods: IR, Vapor phase, hot air oven.  
\* Devices can be cleaned using standard industry methods and solvents.

**Notes:**

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

**Package Information**

Tape & Reel: 5000pcs per reel.

**Effectivity:** Reference documents shall be the issue in effect on the date of invitation for bid.

**Caution:** Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

